

Latchup Detection And Protection (LDAP)

ZES100F

Abstract

The Application Note delineates the unique features and advantages of Latchup Detection And Protection (LDAP), compared with conventional current limiter. In short, LDAP is designed to protect non-rad-hard semiconductor components from radiations, in particular Single-Event-Latchup (SEL) and/or micro-SEL (μ -SEL).

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1. Introduction

ZES LDAP is a radiation-hardened monolithic microchip, dedicatedly designed for space/satellite applications, protecting non-radiation-hardened microchips from radiations, in particular Single-Event-Latchup (SEL) and/or micro-SEL (μ SEL).

SEL is commonly observed as a phenomenon akin to a short-circuit current. On the other hand, μ SEL is not well reported as its current surge is often relatively small, hence mostly unnoticeable. As microchips are getting more advanced and sophisticated, μ -SEL therein is more prevalent.

Figure 1 (a) depicts a waveform of an accumulated μ SEL current from a Commercial-Off-The-Shelf (COTS) FPGA induced by a laser. Multiple μ SEL events are observed and every μ SEL event only incurs a very small increase of current. If a conventional current limiter is implemented to protect this FPGA, the conventional current limiter would miss the first few μ SEL events, hence highly compromising the reliability of the FPGA. Note that the occurrence of these multiple μ SEL events is accelerated during the laser tests. In the actual space environment, the occurrence of the μ SEL event is totally random, and the time interval between two μ SEL events can be weeks or even months.

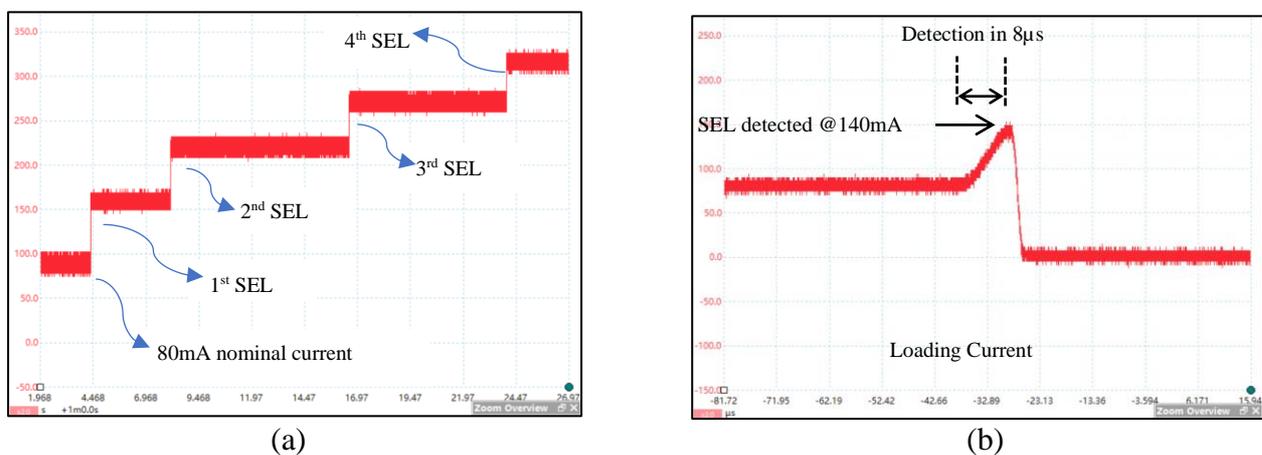


Figure 1 (a) Demonstrations of accumulated μ SELS induced by Laser, (b) detection of μ SEL by LDAP

ZES LDAP is designed to detect both SEL and μ SEL based ZES' proprietary technology. Specifically, ZES LDAP continuously monitors and analyzes the loading current, and is able to intelligently detect the transient profile of SEL and/or μ SEL current, and subsequently performs a power-cycling to protect the FPGA.

**ZES LDAP itself is radiation hardened, immune to any Single-Event Effects including Single-Event Latchup, Single-Event Transient (SET), Single-Event Upset (SEU), etc. of $>110\text{MeV}\cdot\text{cm}^2/\text{mg}$, and to Total Ionized Dose (TID) of $>300\text{Krad}$.

2. ZES LDAP Solution

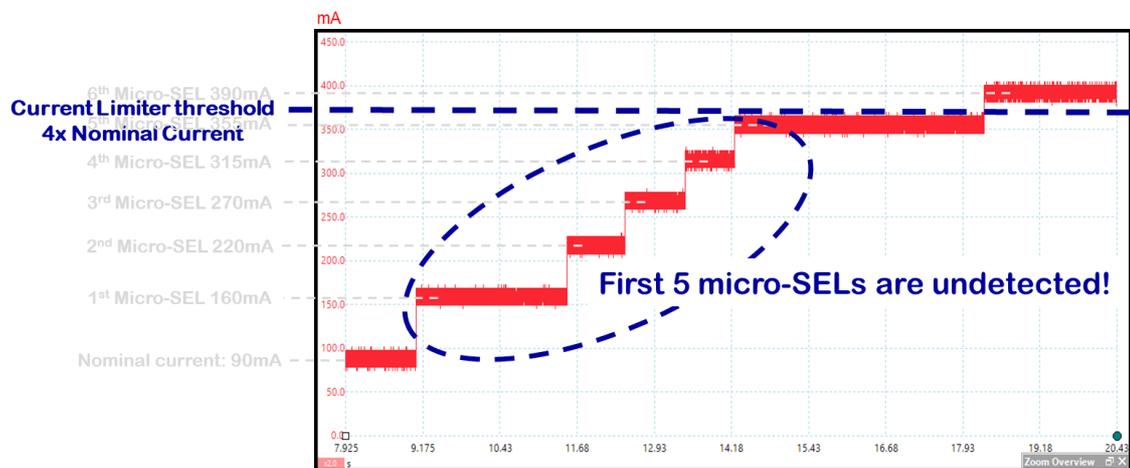
ZES LDAP, embodying ZES' proprietary LDAP along with laser tests, offers unprecedented advantages over the conventional Current Limiter. Specifically, ZES LDAP offers:

- (a) **First level of protection for micro-SEL (μ SEL);**
- (b) **Second level of protection of major-SEL and other current anomalies.**
- (c) **Immunity to false trigger; and**
- (d) **Radiation hardening.**

Each feature will now be delineated in turn.

First, the **features in (a) and (b)** are delineated together as they address a similar problem, SEL, which is well recognized as the top concern for CMOS-based COTS ICs/SoCs in a radiation environment.

The mechanism of SEL has been well established, and consequently, the SEL has been conventionally treated as a general over-current event – we call it major-SEL. However, as COTS ICs/SoCs become advanced and sophisticated, the SEL behavior of these ICs/SoCs also turns to be more complex. Specifically, the SEL events of many advanced COTS ICs/SoCs do not resemble the general over-current events whose current mostly surges to a very high level. Conversely, these SEL events are often localized within a small silicon region, hence exhibiting a low SEL current – we call it micro-SEL (μ SEL). **Figure 2** depicts several μ SEL events in a commercial FPGA, induced by an accelerated laser test, whose μ SEL current is very small, comparable with the nominal operating current. There are two distinctions between major-SEL and μ SEL. First, major-SEL often inflicts a rapid damage to ICs as the induced major-SEL current is mostly high, while μ SEL typically does a postponed damage as the induced μ SEL current is mostly low. Second, the rapid damage by major-SEL often exhibits as burning, while the postponed damage by μ SEL often exhibits as electromigration. Further note that, in a practical radiation environment, the SEL events are totally random, and hence the interval between two μ SEL can be in weeks or even months, unlike that in **Figure 2** as it is the results of an accelerated test.



Y He, et al., J Chang, RADECS Conf, Oct 2022

Figure 2 μ SEL current in a COTS FPGA

At this juncture, the common practice for SEL protections in satellites is a conventional Current Limiter (CL). The CL had been effective in the past as most of the SEL events in traditional CMOS-based COTS ICs are major-SEL. However, it is increasingly challenging to protect μ SEL by the conventional CL. Taking the example in **Figure 2**, wherein the nominal current is 90mA, and the CL threshold is typically set at 360mA, 4X of the nominal current, it can be observed that the conventional CL would miss the first 5 μ SEL events, the elevated SEL current would gradually damage the COTS FPGA due to electromigration, hence highly compromising the reliability of the COTS FPGA.

It is even harder to implement the conventional CL to protect a complex COTS computation system. **Figure 3(a)** illustrates an example of the operation of the complex computation system that embodies a low-computation mode at a low operating current of 20mA and a high-computation mode at a high operating current of 230mA. When μ SEL occurs, the total current including the μ SEL current jumps to 150mA. In this example, designers would find it extremely difficult to set the current limit threshold when the conventional CL is employed. Specifically, if the current limit threshold is set low according to the low operating current as depicted in **Figure 3(b)**, μ SEL can be detected, but the high-computation mode would incur a false trigger. On the other hand, if the current limit threshold is set high according to the high operating current as depicted in **Figure 3(c)**, μ SEL would be detected.

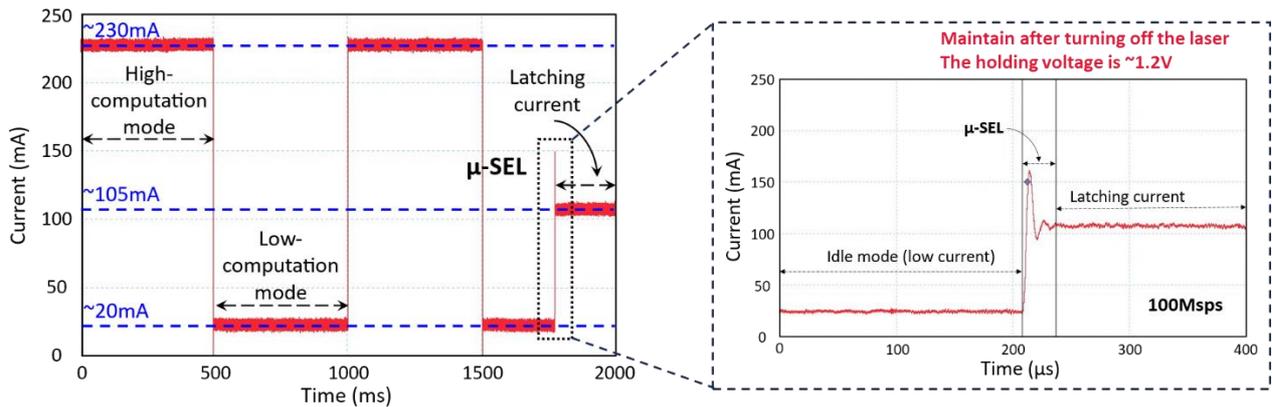


Figure 3(a)

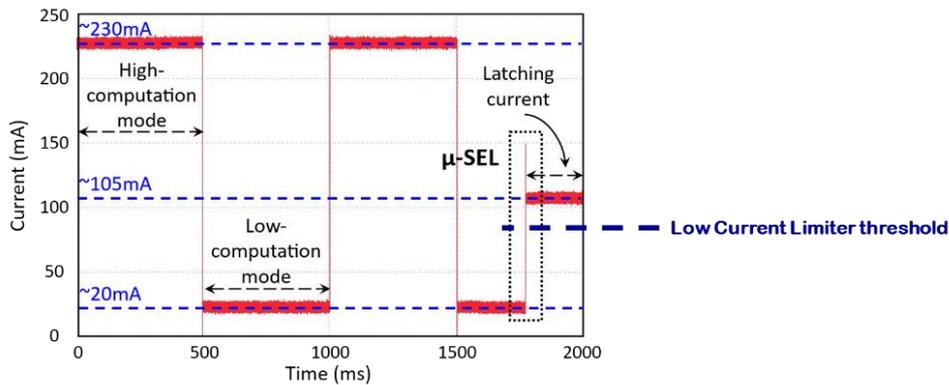


Figure 3(b)

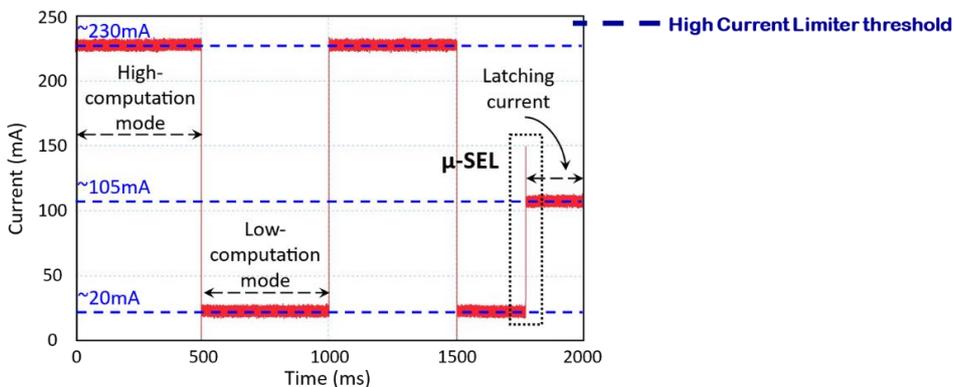


Figure 3(c)

Figure 3 A complex COTS computation system embodying low and high computation currents: (a) μ SEL, (b) protected by a low CL threshold, (c) protected by a high CL threshold

In short, the conventional CL is unable to protect advanced and complex ICs/SoCs from SEL, in particular μ SEL.

ZES LDAP embodies two levels of protection. The first level of protection is to detect μ SEL by a proprietary SEL current detector, which intelligently detects μ SEL by analyzing and distinguishing the transient μ SEL current profile. **Figure 4** depicts the waveforms of the μ SEL current when being detected and subsequently protected by ZES LDAP. It can be observed that the μ SEL detection only takes $8\mu\text{s}$, and the μ SEL only increases by 60mA ($=140\text{mA}-80\text{mA}$).

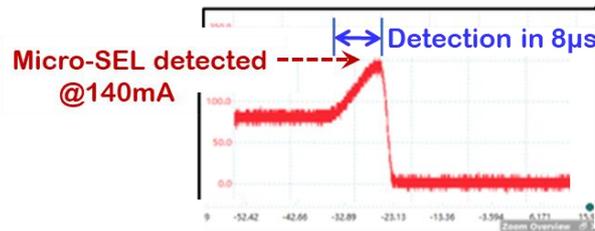


Figure 4 μ SEL detection and protection by ZES LDAP

The second level of protection serves to complement the first level of protection by detecting major-SEL and other current anomalies. The second protection is akin to the conventional CL, wherein a current threshold is implemented. However, as a complementary level of protection, it typically embodies a current threshold far away from the operating current, hence only being triggered when a destructively high current appears; note that this scenario is largely rare in real applications.

In short, ZES LDAP provides unprecedented detection and protection for μ SEL, major-SEL and other current anomalies.

Second for **feature (c)**, ZES LDAP is advantageous over the conventional CL as it is designed to be immune to false triggers. Three scenarios may introduce false triggers. The first is an operating current swing between a low-computation mode and a high-computation mode. As mentioned above for **Figures 3(b) and 3(c)**, the false trigger happens when the current threshold of the conventional CL is low, but setting the current threshold high to avoid the false trigger may incur protection failures. ZES LDAP doesn't exhibit any false triggers in this case. Specifically, its first level of protection is innately immune to this scenario, as ZES LDAP is designed to only detect the unique transient profile of the SEL current, which is very distinct from the transient current swinging from low to high. Further, its second level of protection, as the complementary protection, can be set higher than the current at the high-computation mode. The second is a transient operating current spike. The current spike is typically large and fast, and may temporarily exceed the current threshold of the conventional CL, hence triggering the protection falsely. A blank time is often implemented to avoid this. ZES LDAP is also immune to this. Specifically, akin to the first, its first level of protection can intelligently distinguish the transient SEL current from the transient current spike, and its second level of protection is also insensitive to it as a similar blank time is realized therein. The third is a gradual operating current increase over an operational lifetime, and this current increase is largely induced by radiation. As the current threshold of the conventional CL is mostly fixed, false trigger could happen to the conventional CL at a later juncture of the operational lifetime. On the other hand, for ZES LDAP, its first level of protection is innately insensitive to the gradual current increase, and its second level of protection cannot be falsely triggered as its threshold is set high.

In short, ZES LDAP's intelligent detection algorithm is able to unambiguously differentiate the SEL current from various behaviors of the operating current.

Third for **feature (d)**, ZES LDAP is radiation hardened by means of ZES' proprietary Radiation Hardening By Design (RHBD). ZES LDAP has been tested to be radiation hardened at least 300krad TID, and at least $110\text{MeV}\cdot\text{cm}^2/\text{mg}$ for Single Event Effects, including SEL, SET, SEU etc.

ZES LDAP has been demonstrated to successfully protect various COTS ICs/SoCs both on ground and in outer space. These COTS includes simple analog ICs like AD8629, mixed-signal ICs like AD7888, and complex digital SoCs like PIC16F688, ProASIC3, Kintex XC7K160T, SAMD21G18A, etc. On grounds, it has been demonstrated that ZES LDAP is able to detect and subsequently protect every SEL event under heavy-ions and laser tests. In space, ZES LDAP has successfully achieved flight heritage in 4 satellites. In one of the missions, ZES LDAP was directly benchmarked with the conventional CL, wherein one board embodied ZES LDAP protecting a COTS, and the other board, which is adjacently implemented, embodied the conventional CL protecting the COTS.

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Over 18 months of mission time, the flight data showed that ZES LDAP successfully detected and protected the COTS from SELs 41 times, and the conventional CL didn't exhibit any protection at all – this observation was consistent with the ground testing data before the launch.

In summary, ZES LDAP offers unprecedented benefits of protecting advanced COTS ICs/SoCs from various current anomalies in space including μ SEL, hence truly enable COTS into space missions.

3. Application of ZES LDAP

ZES LDAP is implemented on the power supply rail to monitor and protect the COTS from current anomalies in particular SEL. **Figure 5** depicts a general Power line connection, however not every powerline is vulnerable to SEL. ZES' LDAP required only apply on the SEL-sensitive powerline(s).

The laser test is able to identify which powerline(s) is sensitive to SEL. In addition to SEL, SET/SEU can also be evaluated and subsequently mitigated by **ZES' voter****.

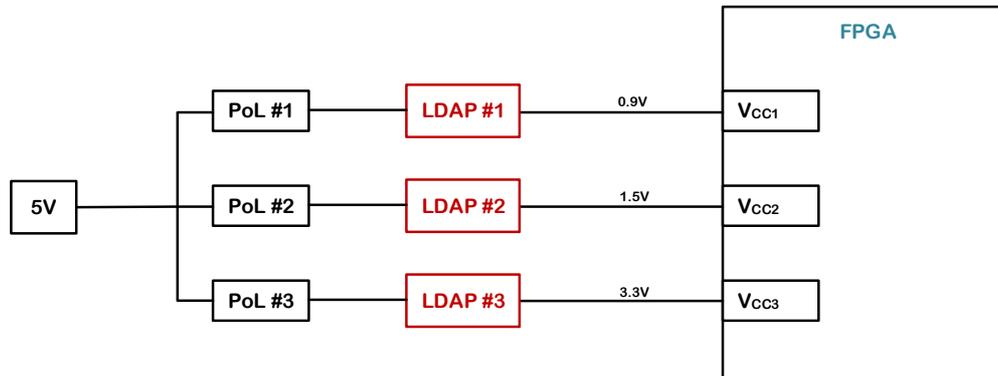


Figure 5 ZES' Recommended Solution of LDAP for COTS

** - ZES' voter is ZES400 radiation hardened monolithic microchip with Triple-Modular-Redundancy (TMR) system.

Depending on various parameters that are embodied by radiation particles and COTS ICs, the SEL current profiles induced by each radiation hit can be different – this is confirmed by our observations of numerous radiation tests and laser tests of many different COTS ICs.

The conventional Current Limiter (CL), which offers SEL protection only when the SEL current exceeds a predetermined threshold (e.g. 3-4x of the nominal current), is grossly rudimentary and highly inadequate to handle the sophisticated and yet different SEL current profiles arising from advanced COTS ICs (e.g. FPGA) in modern satellites.

Conversely, ZES' solution, embodying Latchup Detection And Protection (LDAP), offers a very unique SEL detection and protection by means of intelligently monitoring the unique signature of the SEL current, and hence offering unprecedented advantages over the conventional Current Limiter solution. In the following, we will first explain why the employment of the conventional Current Limiter is flawed, followed by the benefits of ZES' LDAP solution. The description is based on a power reference design for an exemplar FPGA **Figure 5**, wherein the 5V bus is converted to 3 powerlines at different supply voltages.

4. Common issue with conventional Current Limiter Protection

During radiation and laser tests, it has been observed the power cycling by the conventional Current Limiter is inadequate for the removal of the SEL current in many advanced COTS ICs including FPGAs. Below **Figure 6(a)** depicts the SEL current when SEL occurs, wherein the SEL current flows from V_{DD} to Ground via the circuits latching up. After the SEL current increases accumulatively until triggering the conventional Current Limiter. Subsequent to the triggering, V_{CC} is disconnected from the powerline and the SEL current stops to flow from the powerline to Ground. However, the SEL current is not removed.

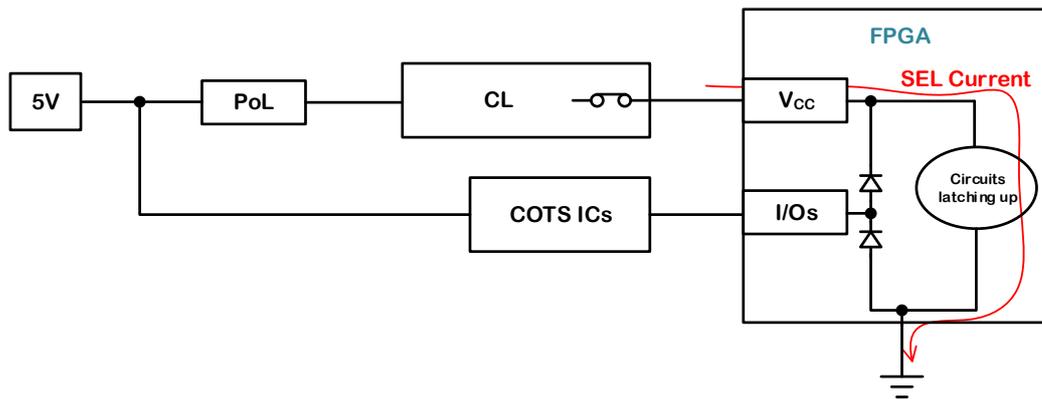


Figure 6(a)

Below **Figure 6(b)** depicts the SEL current after the conventional Current Limiter disconnects V_{CC} from the powerline, wherein the SEL current flows from I/Os sustained by preceding COTS ICs to Ground. In short, the conventional Current Limiter cannot protect the FPGA from SEL in this case.

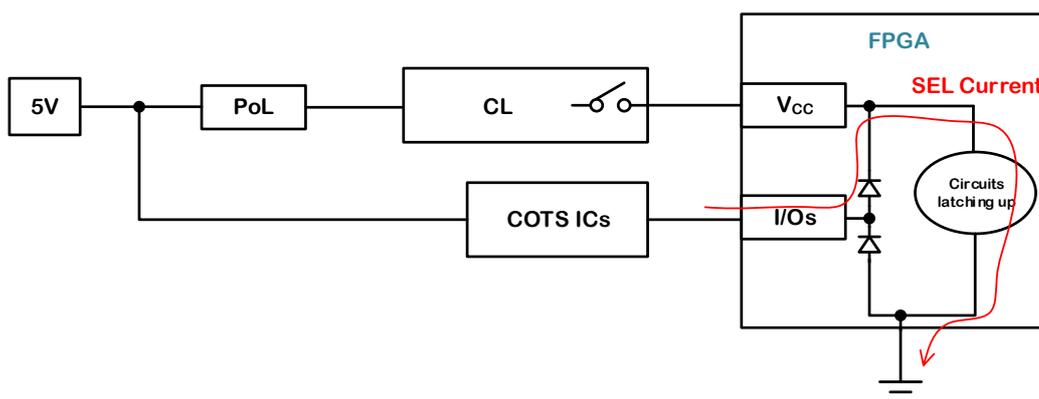


Figure 6(b)

Figure 6 SEL behavior via I/Os: (a) SEL occurs (b) SEL is not removed by Current Limiter

From the above case with the I/O issue, performing a laser test to evaluate ZES' solution integrated into conventional Current Limiter, as depicted in below **Figure 7**. When an SEL occurrence is detected by any LDAP, a flag signal is sent to OBC (On-Board-Computer) to demand the disconnection of 5V bus from other components. Note that ZES' solution may have several flag (Power Good, PG) signal variations depending on the complexity of FPGA.

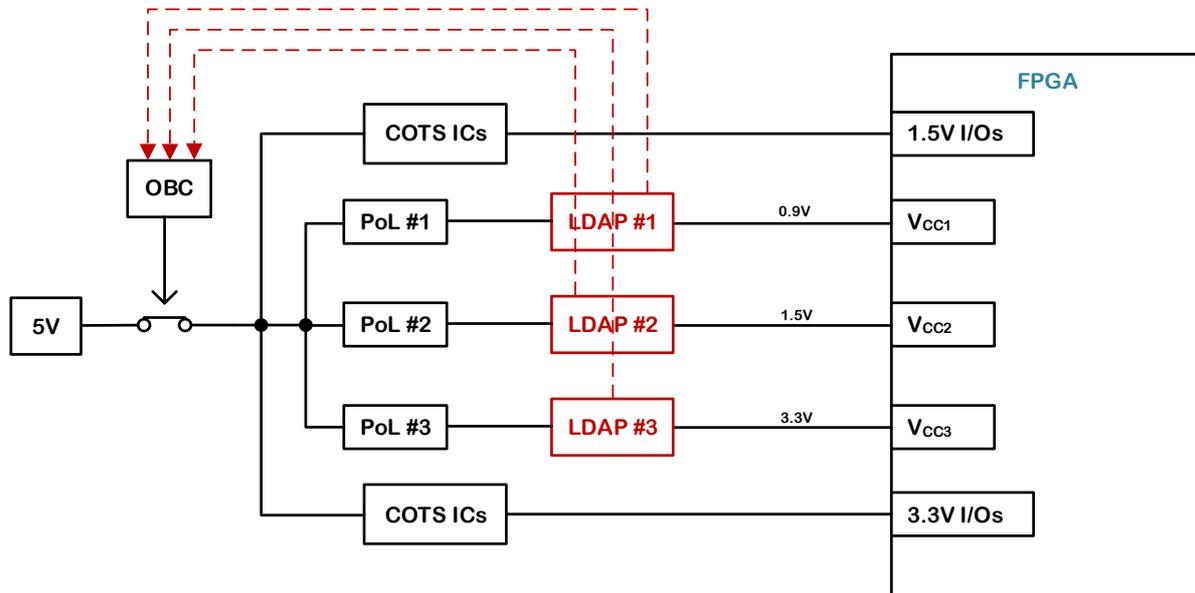


Figure 7 ZES' Recommended Solution of LDAP with OBC

Furthermore, in some FPGA applications, power sequencing during power-on is required, or multiple powerlines are connected internally (e.g. via back-to-back diodes). In such cases, if one powerline exhibits SEL, all powerlines require synchronized reset. Below **Figure 8** depicts ZES' recommended solution that allows the synchronized reset by interconnecting multiple LDAPs. Note that ZES' solution of synchronized Reset may have several reset variations depending on the behaviors of the powerlines of FPGA.

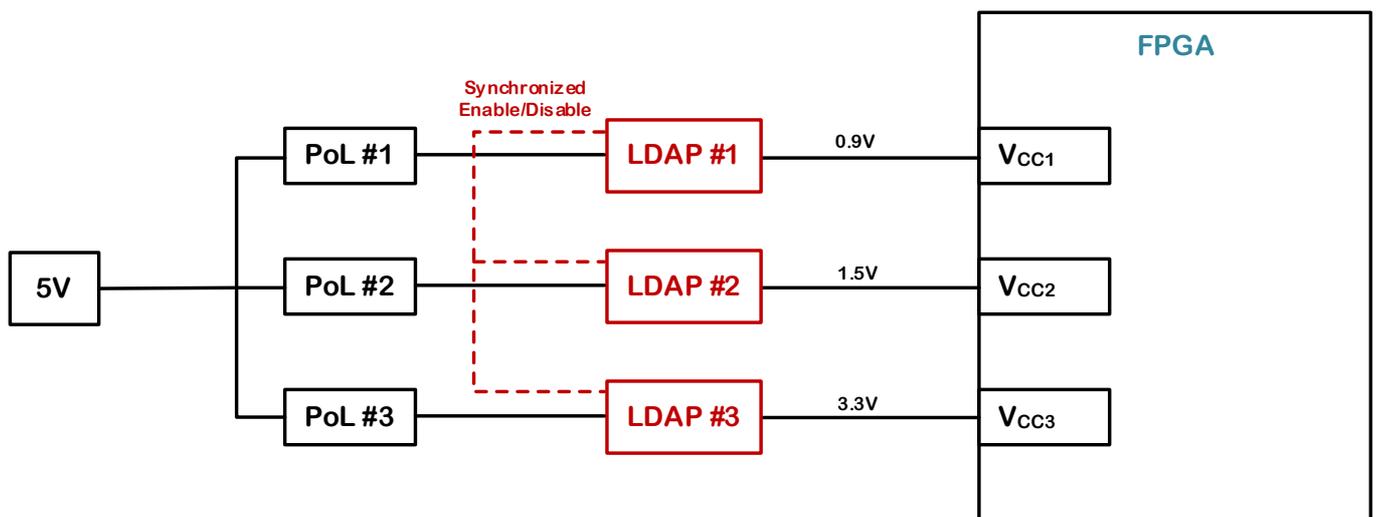


Figure 8 ZES' Recommended Solution of synchronized reset

5. Implementation of ZES LDAP

The core of ZES LDAP consists of current sensing, an intelligent latch-up detector, recovery, and telemetry functions designed for high reliability system implementation.

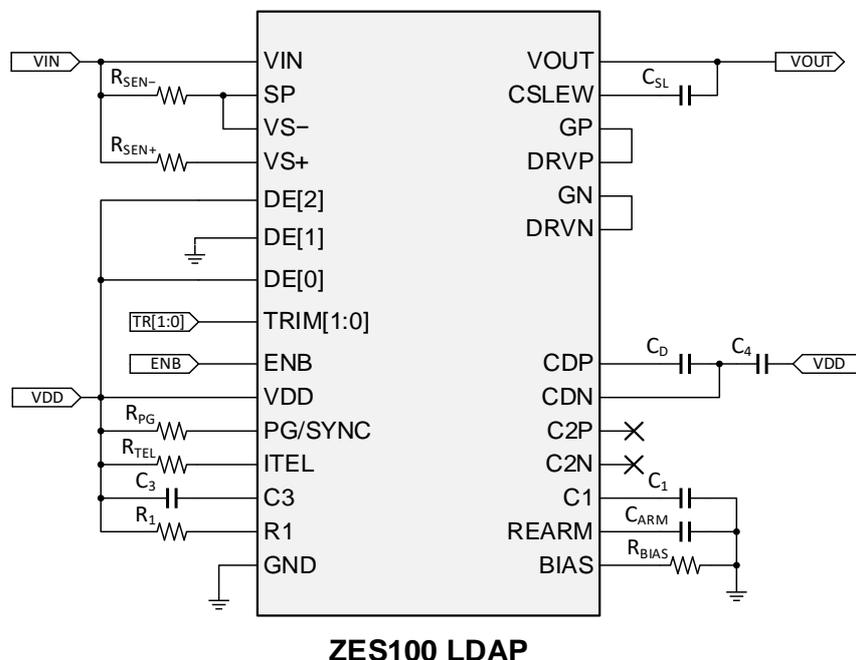


Figure 9 Typical application circuit implementation

Table 1 Typical values of implementation for ZES100 LDAP at the current limit of ~500mA, current ratio of ~500

Symbol	Typical Value	Unit
R_{SEN-}	10	m Ω
R_{SEN+}	5	Ω
R_{PG}	100	k Ω
R_{TEL}	1	k Ω
R_1	18	k Ω
R_{BIAS}	470	Ω
C_1	10	nF
C_3	10	nF
C_4	10	nF
C_D	10	nF
C_{SL}	10	nF
C_{ARM}	1	nF

5.1 Current Sensing

ZES LDAP has a built-in current sensor to read the current through V_{OUT} , i.e., the output/load current I_{OUT} as the sensed current I_{SEN} with a certain current sensing ratio. The current sensing ratio between I_{OUT} and I_{SEN} can be customized using R_{SEN-} and R_{SEN+} resistors by the following relationship.

$$r = \frac{I_{OUT}}{I_{SEN}} = \frac{I_{OUT,MAX}}{I_{SEN,MAX}} = \frac{R_{SEN+}}{R_{SEN-}}$$

The current sensing ratio depends on the load and the absolute maximum rating ZES LDAP internal sense current branch (~2mA). For example, for a Device Under Protection (DUP) with max supply current, $I_{OUT,MAX}$ of 500mA, we can limit the maximum sensed current $I_{SEN,MAX}$ to 1mA (additional derating) to obtain current sensing ratio of 500. If the R_{SEN-} resistance is set to be 10mΩ, then the R_{SEN+} resistance is 5Ω. It is recommended to design the minimum voltage drop across R_{SEN-} of 5mV.

The current sensing ratio accuracy may be affected by several factors such as parasitic resistance of PCB traces, resistors tolerance, internal offset, etc. To mitigate the impact of parasitic resistance of PCB traces, it is recommended that the PCB route from R_{SEN-} to V_{S-} (low current path for sensing) is isolated from the route from R_{SEN-} to SP (high current path). Below **Figure 10** depicts a PCB layout example where the two paths are only connected together at one of the R_{SEN-} pads such that the voltage sensed by V_{S-} will be less affected by the voltage drop due to parasitic resistance of the PCB trace.

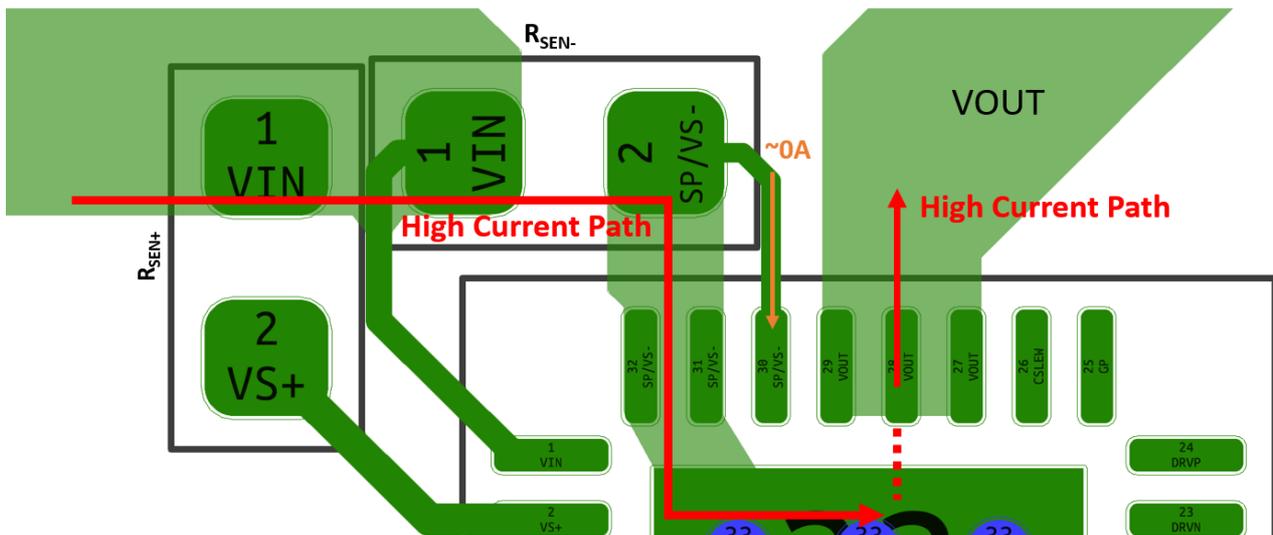


Figure 10 PCB layout recommendation for an optimized current sensing accuracy

5.2 Input and Output Capacitors

Integration of ZES LDAP into a system requires some considerations in the selection of both input capacitor C_{IN} and output capacitor C_{OUT} as these capacitors could induce sensitivity and reliability issues. **Figure 11** depicts the typical placement of C_{IN} and C_{OUT} . It is recommended to keep C_{OUT} to a low value ($\ll 100\text{nF}$) when possible.

A high C_{OUT} may hinder the ZES LDAP's current sensing, as most of the DUP's dynamic supply current will be drawn from C_{OUT} instead of ZES LDAP. Furthermore, it is strongly recommended that $C_{IN} \gg C_{OUT}$ to prevent reverse bias current from V_{OUT} to V_{IN} .

For higher reliability, V_{OUT} should remain lower than V_{IN} such that there is not reversed bias internally.

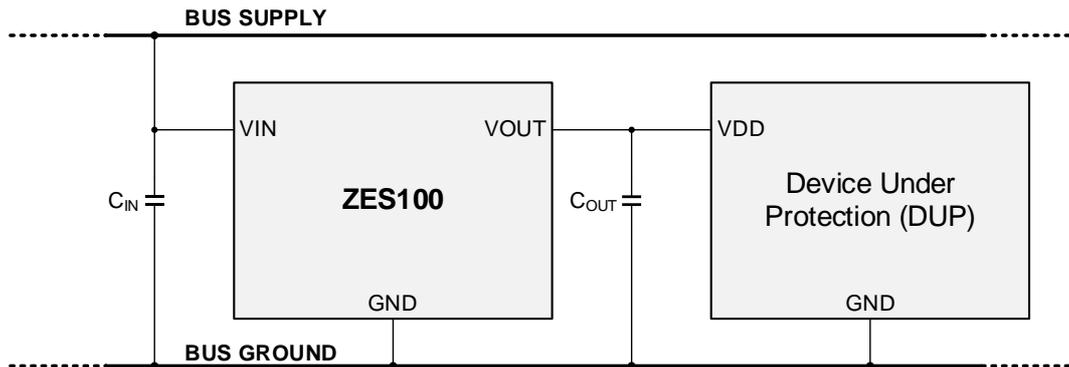


Figure 11 Input and output capacitors placement in a typical application circuit

5.3 External Control (MCU/FPGA) of Power Cycling (counting SEL occurrence)

In some applications, there is a need for extra flexibility in controlling the power cycling sequence as it could be disruptive to other parts in a system. There are several ways to configure ZES100 for such application.

Error! Reference source not found. depicts an example of ZES100 configuration where the recovery sequence (power cycling) is externally controlled by a microcontroller unit MCU. The DRVN pin serves to provide a flag signal to the MCU. DRVN = "1" means an SEL/overcurrent is detected, while DRVN = "0" means no overcurrent/SEL is detected.

When there is SEL/overcurrent flag signal detected by MCU, the MCU can count the number of SEL and delay the power cycling until the suitable time to activate the power cycle.

The MCU can activate the power cycling through both O1 and O2 (Output1 and 2) pins to ZES100 GP and GN pin. GP and GN pins are the gate pin of the internal power PFET and NFET switches, respectively.

O1 = "0" means turn on internal PFET and O2 = "0" means turn off internal NFET switches to turn ON V_{OUT}.

O1 = "1" means turn off internal PFET and O2 = "1" means turn on internal NFET switches to turn OFF V_{OUT}.

When the pull-down switch is unnecessary, the internal NFET switch can be disabled by connecting GN pin to GND instead.

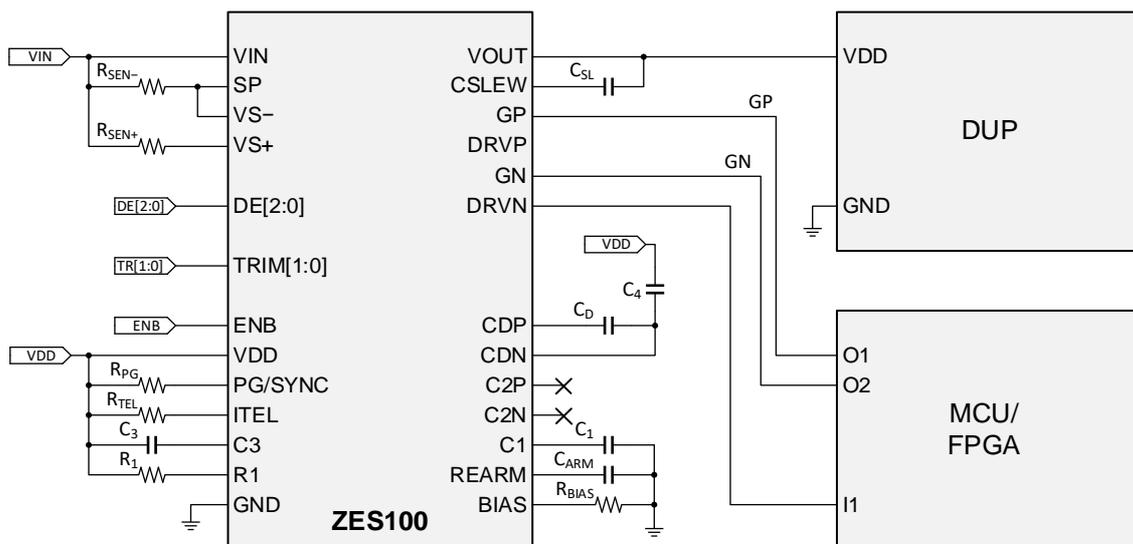


Figure 2 An example of ZES100 configuration with external control of power cycling

5.5 External Power Switches (for higher I_{OUT})

The ZES100 LDAP has a built-in power PFET switch, and a pull-down NFET switch (in series with a 50 Ω resistor). Both the built-in power switches are de-rated and their gates are accessible through GP and GN, respectively. The max drain-source current of the power PFET is 500mA at 125°C. These power switches can be driven by ZES100's drivers DRVP and DRVN. To use the built-in power switches, simply connect DRVP to GP, and DRVN to GN as depicted in above **Figure 9**.

The ZES100 also supports the use of an external power switch (P-Channel MOSFET) to deliver higher I_{OUT} to load. **Figure 14** depicts an example circuit configuration to implement ZES100 with an external power P-Channel MOSFET.

* Infineon IRHLNA797064, IRHLNA793064 Radiation-Hardened 60 V, 56 A P-channel Power MOSFET.

Recommendation for the selection of external switch, the Gate-Source Threshold Voltage $V_{gs(th)} > V_{IN} - 0.2V$.

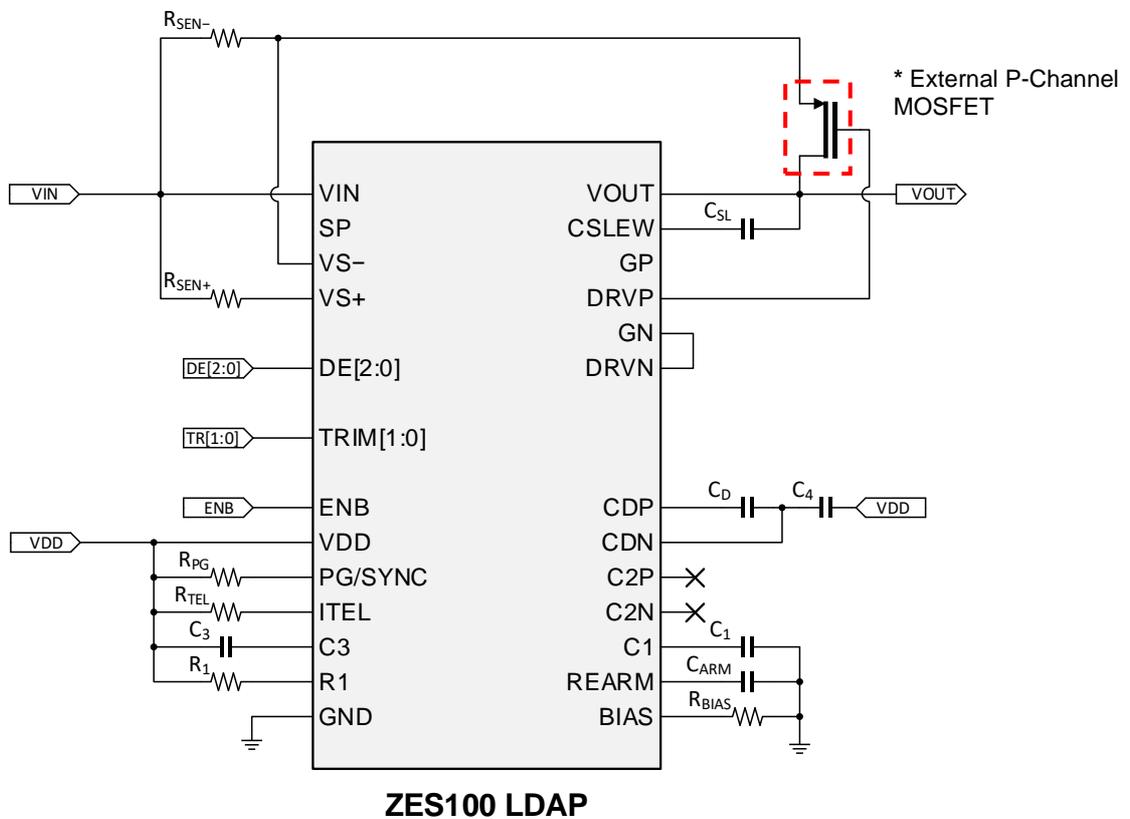


Figure 14 Circuit configuration to implement ZES100 with an external power switch.

Appendix**Revision History**

Revision No.	Notes	Date
Rev 1.0	Preliminary version	Sept, 2022
Rev 3.1	Preliminary version	Sept, 2023
Rev 3.2	Preliminary version	Nov, 2023
Rev 3.3	Initial Release	Oct, 2024

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